AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (previously presented): A thin film analyzing method for analyzing a constituent of a thin film, which comprises a cutting step of cutting the thin film obliquely and an analyzing step of analyzing the cut section of the thin film,

wherein the analyzing step is a step for measuring a distribution state of a specific component in the cut section of the thin film, and

wherein the distribution state of the specific component is analyzed by TOF-SIMS in the analyzing step.

2. (original): A thin film analyzing method according to claim 1, wherein the thin film is a thin film formed on a support.

3. (original): A thin film analyzing method according to claim 1, wherein the thin film has a multilayered structure.

4. (original): A thin film analyzing method according to claim 2, wherein the thin film is formed on a support and has a monolayered or multilayered structure.

5. (canceled).

6. (canceled).

7. (canceled).

8. (canceled).

9. (previously presented): A thin film analyzing method for analyzing a constituent of a thin film, which comprises a cutting step of cutting the thin film obliquely and an analyzing step of analyzing the cut section of the thin film,

wherein the analyzing step is a step for measuring a distribution state of a specific component in the cut section of the thin film, and

wherein the distribution state of the specific component is analyzed by μ-ESCA in the analyzing step.

10. (canceled).

11. (original): A thin film analyzing method according to claim 1, wherein the thin film is cut with a microtome to which a cutting edge made of glass is fitted in the cutting step.

12. (original): A thin film analyzing method according to claim 4, wherein the thin film is cut with a microtome to which a cutting edge made of glass is fitted in the cutting step.

13. (original): A thin film analyzing method according to claim 11, wherein an edge angle of the cutting edge made of glass is 55° or less.

14. (original): A thin film analyzing method according to claim 12, wherein an edge angle of the cutting edge made of glass is 55° or less.

15. (original): A thin film analyzing method according to claim 1, wherein an angle for the cutting is set to 5° or less in the cutting step, thereby enlarging an area of the cut section in a film thickness direction 10 to 2800 times as compared with a case in which the thin film is cut perpendicularly to the surface of the thin film.

16. (original): A thin film analyzing method according to claim 4, wherein an angle for the cutting is set to 5° or less in the cutting step, thereby enlarging an area of the cut section in a film thickness direction 10 to 2800 times as compared with a case in which the thin film is cut perpendicularly to the surface of the thin film.

17. (original): A thin film analyzing method according to claim 1, wherein the thin film is a photosensitive thin film.

18. (original): A thin film analyzing method according to claim 17, wherein the photosensitive thin film is an image recording layer comprising a water-insoluble and alkali-soluble resin, an infrared ray absorber, and a colorant.

19. (original): A thin film analyzing method according to claim 1, wherein the thin film is a photosensitive thin film which is formed on a support and comprises a water-insoluble and alkali-soluble resin, an infrared ray absorber, and a colorant, and in the analyzing step the distributions of the infrared ray absorber and the colorant in the thin film are analyzed.

20. (previously presented): A thin film analyzing method according to claim 9, wherein the thin film is a thin film formed on a support.

21. (previously presented): A thin film analyzing method according to claim 9, wherein the thin film has a multilayered structure.

22. (previously presented): A thin film analyzing method according to claim 9, wherein the thin film is formed on a support and has a monolayered or multilayered structure.

23. (previously presented): A thin film analyzing method according to claim 9, wherein the thin film is cut with a microtome to which a cutting edge made of glass is fitted in the cutting step.

24. (previously presented): A thin film analyzing method according to claim 9, wherein the thin film is cut with a microtome to which a cutting edge made of glass is fitted in the cutting step.

25. (previously presented): A thin film analyzing method according to claim 23, wherein an edge angle of the cutting edge made of glass is 55° or less.

26. (previously presented): A thin film analyzing method according to claim 24, wherein an edge angle of the cutting edge made of glass is 55° or less.

27. (previously presented): A thin film analyzing method according to claim 9, wherein an angle for the cutting is set to 5° or less in the cutting step, thereby enlarging an area of the cut section in a film thickness direction 10 to 2800 times as compared with a case in which the thin film is cut perpendicularly to the surface of the thin film.

28. (currently amended): A thin film analyzing method according to claim ~~9~~22, wherein an angle for the cutting is set to 5° or less in the cutting step, thereby enlarging an area of the cut section in a film thickness direction 10 to 2800 times as compared with a case in which the thin film is cut perpendicularly to the surface of the thin film.

29. (previously presented): A thin film analyzing method according to claim 9, wherein the thin film is a photosensitive thin film.

30. (previously presented): A thin film analyzing method according to claim 29, wherein the photosensitive thin film is an image recording layer comprising a water-insoluble and alkali-soluble resin, an infrared ray absorber, and a colorant.

31. (previously presented): A thin film analyzing method according to claim 9, wherein the thin film is a photosensitive thin film which is formed on a support and comprises a water-insoluble and alkali-soluble resin, an infrared ray absorber, and a colorant, and in the analyzing step the distributions of the infrared ray absorber and the colorant in the thin film are analyzed.